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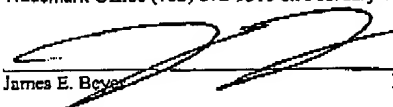
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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

## Application of

Applicants : Salman Akram  
Serial No. : 09/992,580  
Filed : November 16, 2001  
Title : **DIE STACKING SCHEME**  
Docket No. : MIO 0072 VA  
Examiner : N/A  
Art Unit : 2815  
Confirm. No. : 9954

CERTIFICATE OF FACSIMILE TRANSMISSION  
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Trademark Office (703) 872-9318 on February 14, 2002.

  
James E. Beyer

Reg. No. 39,564

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

## PRELIMINARY AMENDMENT

In the Claims:Please ~~cancel~~ claims 19, 21, 22 and 45-51.

Please add new claims 52-56.

The entire set of presently pending claims has been reproduced below for the  
convenience of the Examiner. New claims and cancelled claims are indicated as such in the  
parenthetical following each claim number.

19. (Cancelled)

20. A method of stacking a plurality of semiconductor die, said method comprising:  
providing a substrate;  
providing a first semiconductor die including a pair of major surfaces, wherein  
one of said pair of major surfaces of said first die defines a first active  
surface,

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